

REV.	ECN NO.	DESCRIPTION	DRWN	APPD.	DATE
REV	ECN_NO.	DESCRIPTION	DR.	APPD.	DATE

SPEC:

Current Rating: 3Amps

Insulator Resistance: 5000mΩ Min

Dielectric Withstanding: AC 500V

Operating Temperature: -40° to+105°

Contact Material: Copper alloy T=0.25

Insrlator Material:Polyester,UL 94V-0 LCP

Finish :

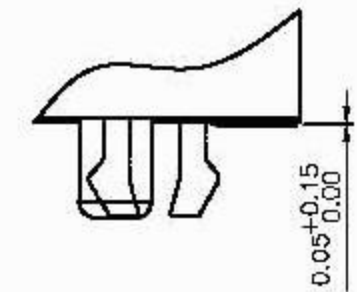
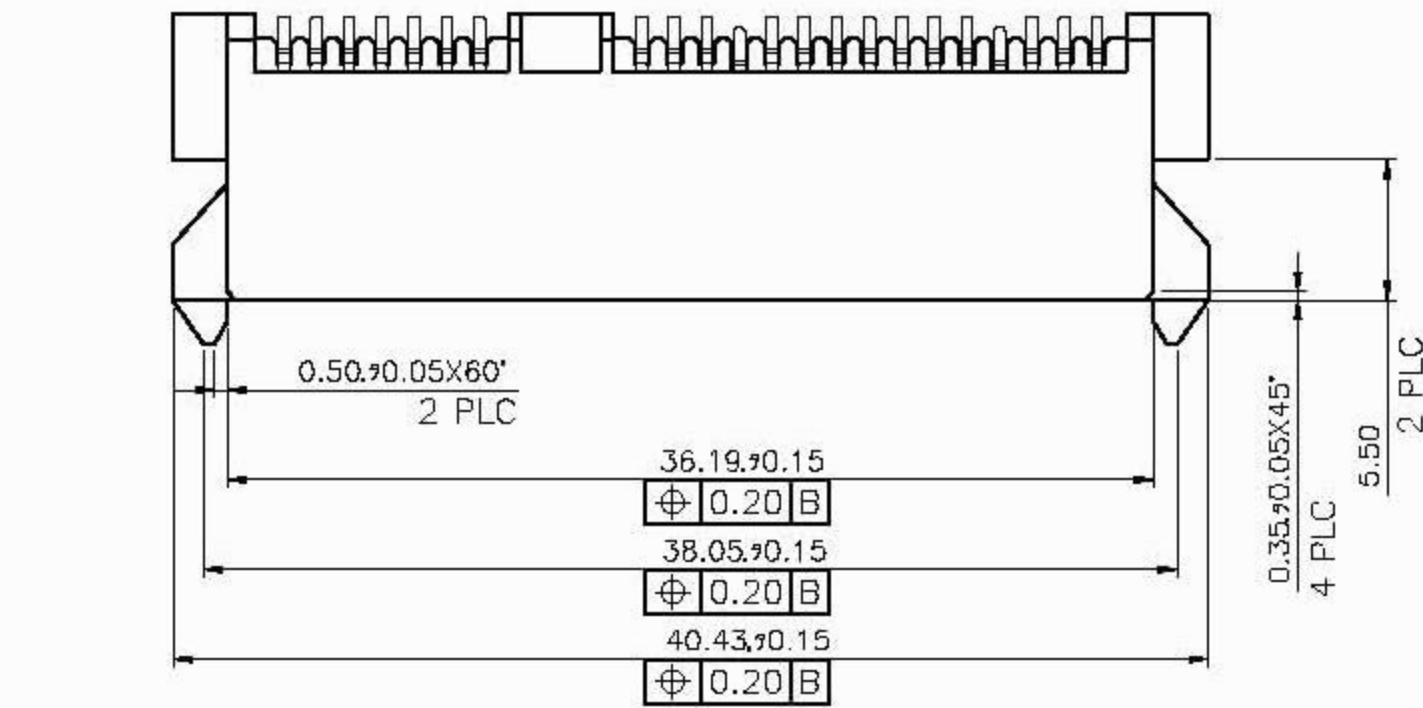
Gold/tin plating on contact area

100u" min. Tin PLating on soldertails

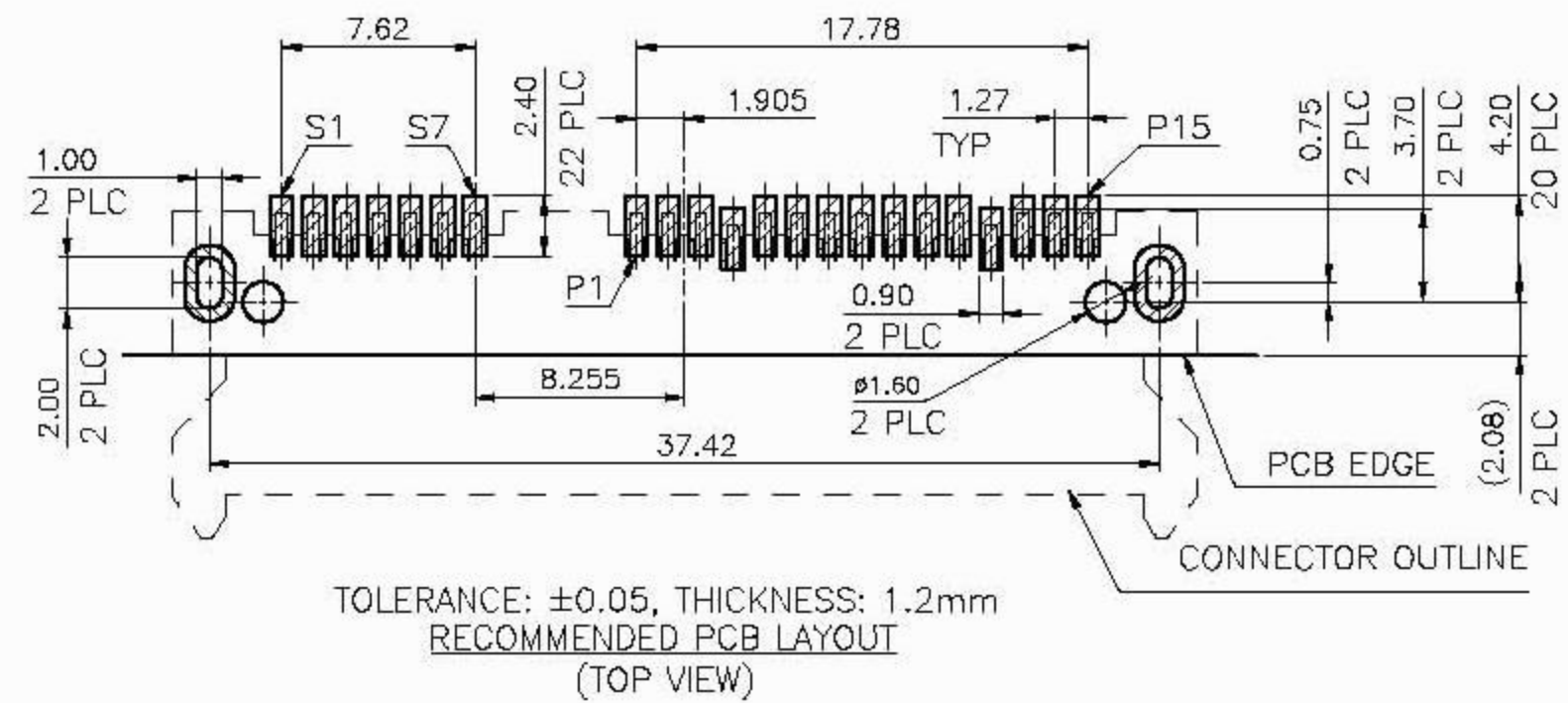
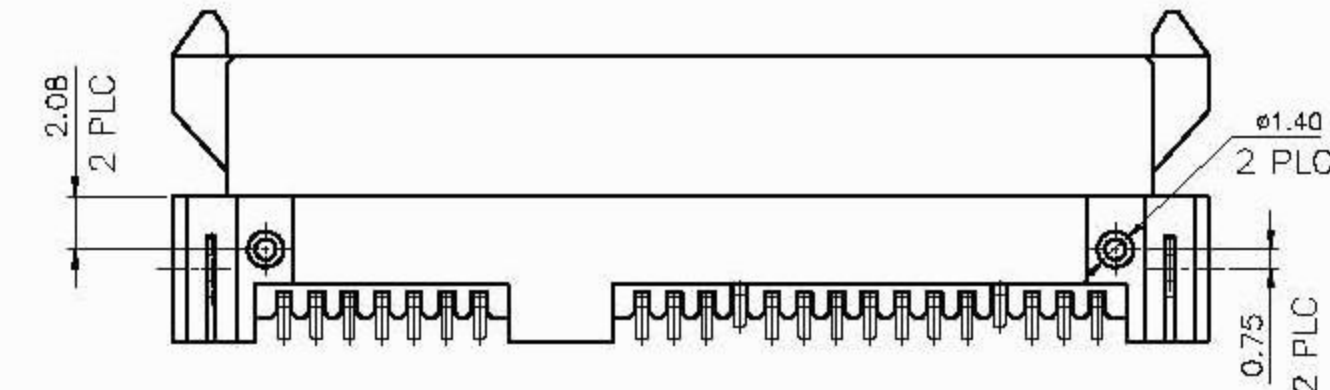
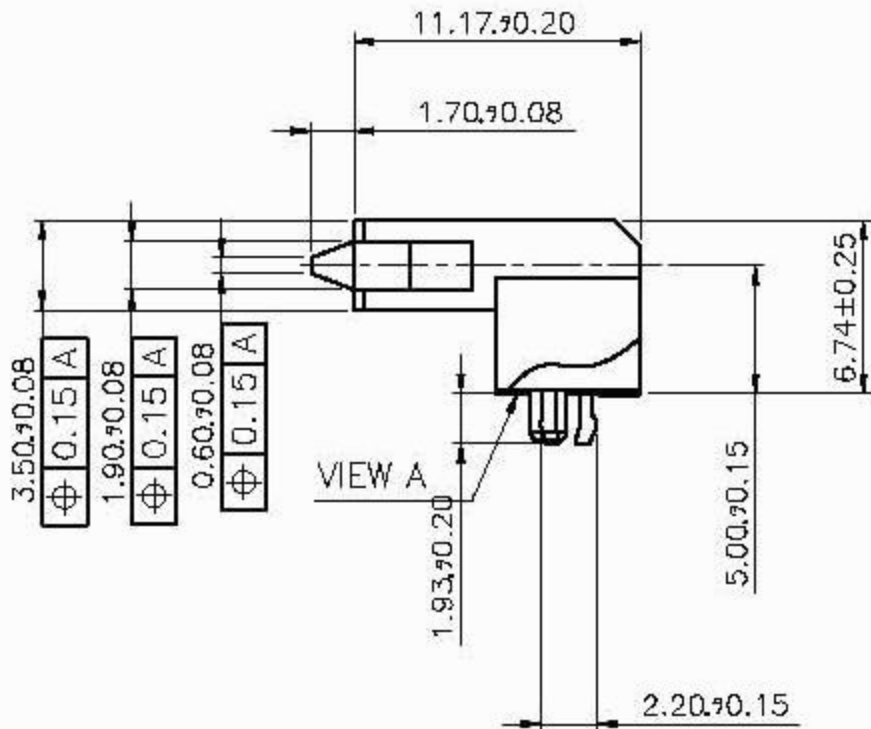
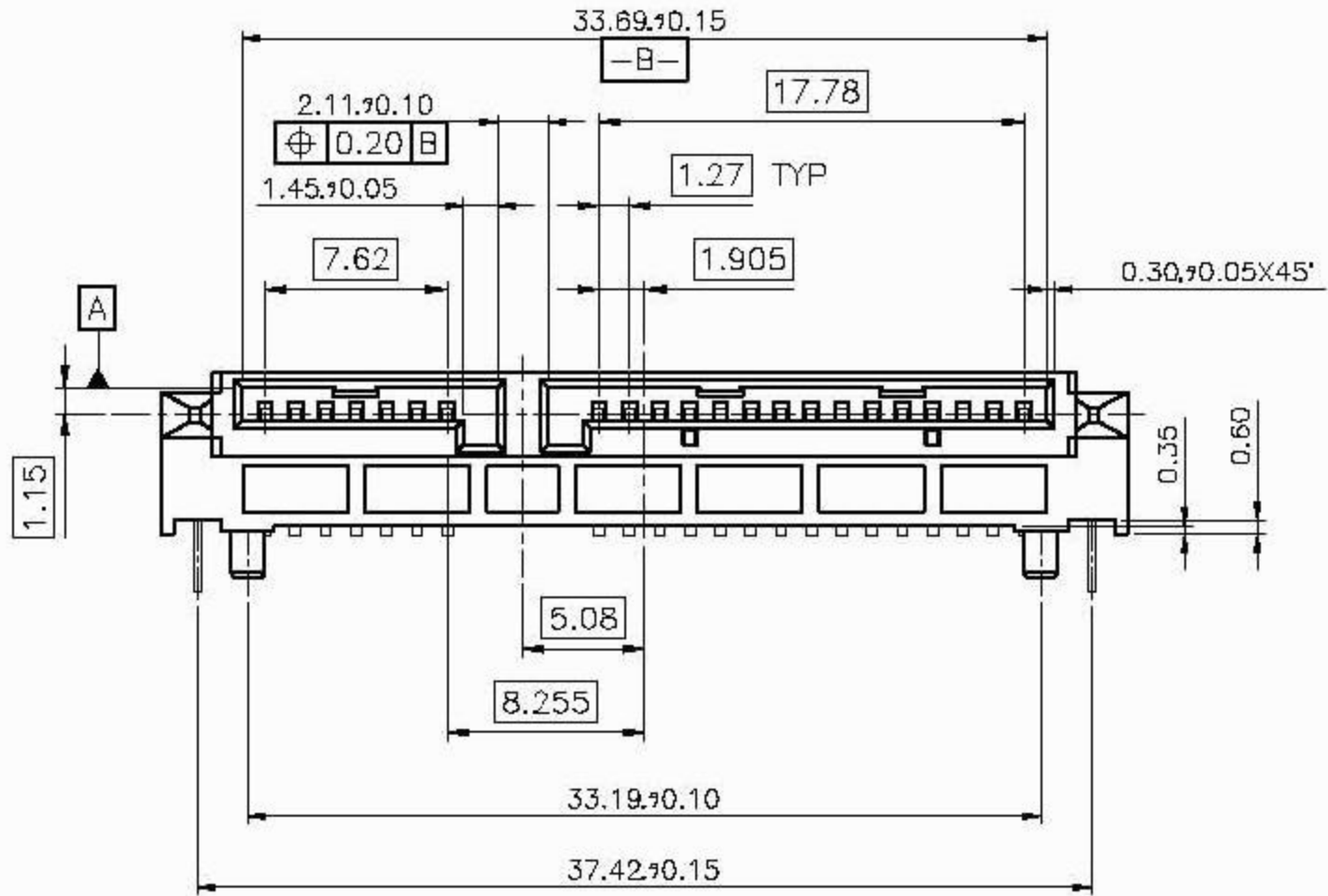
50u" min.nickel under plating over all tin,

Max.Processing Temp:

230C° for 30-60seconds(260C° for 10 secinds)



VIEW A
SCALE 2:1



PART NAME	Q' TY	Material
CONTACT	22	C5191R-H, GOLD FLASH
BOARDLOCKS	2	C2680R-H, TIN 100μ"
HOUSING	1	LCP+30%GF, BLACK

UNITS	SCALE	REV.	SHEET
mm	SCALE	REV.	PAGE
GENERAL TOLERANCE		DATE	D_DATE
0.0		DR.	DESIGNER
0.0		CHK.	
0.0		APPD.	
0.0			

L&X 深圳市连欣科技有限公司			
TITLE			
SATA7+15P 板下6.74 SMT成品			
MAT'L		FINISH	
MATERIAL		FINISH	
DWG.NO.		PART NO.	
DWG_NO.		XUTS-22674-0127	
C		SIZE	
		A4	